

Appl. No. 09/665,034  
Amdt. Dated 12/16/2004  
Reply to Notice of Allowance mailed 10/06/2004

**IN THE CLAIMS**

Please cancel claims 17, 41, and 54 without prejudice.

The following listing of claims replaces all prior versions, and listings, of claims in the application:

1-13. (Cancelled).

14. (Previously Presented) The method as recited in claim 15, wherein  
the conductive strip is formed by plating a conductive material onto the inner side surface  
of the bond shelf.

15. (Previously Presented) A method for assembling an electronic package, comprising:  
forming a housing which has a bond pad located on a top surface of a bond shelf, the  
bond shelf having an inner side surface along a thickness of the bond shelf;  
forming a conductive strip lengthwise along the inner side surface of the bond shelf; and  
removing a portion of the conductive strip along the inner side surface of the bond shelf  
to form a pair of separate conductive strips lengthwise along the inner side surface of the bond  
shelf, the portion of the conductive strip is removed by drilling a portion of the inner side surface  
of the bond shelf including the conductive strip.

16. (Previously Presented) The method as recited in claim 15, further comprising:  
mounting an integrated circuit to the housing and connecting the integrated circuit to the

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bond pad.

17. (Cancelled)

18. (Previously Presented) The method as recited in claim 15, wherein  
the conductive strip is formed along the inner side surface of the bond shelf by  
masking surfaces of the bond shelf except for portions of the bond shelf to be  
plated, the inner side surface of the bond shelf being unmasked, and  
plating a conductive material onto the inner side surface of the bond shelf.

19. (Previously Presented) The method as recited in claim 18, wherein  
the conductive material is copper, and  
the conductive strip is further formed by plating gold onto the copper.

20. (Previously Presented) A method for assembling an electronic package, comprising:  
forming a housing which has a bond pad located on a top surface of a bond shelf, the  
bond shelf having an inner side surface along a thickness of the bond shelf;  
forming a conductive strip lengthwise along the inner side surface of the bond shelf; and  
removing a portion of the conductive strip along the inner side surface of the bond shelf  
to form a pair of separate conductive strips lengthwise along the inner side surface of the bond  
shelf, the portion of the conductive strip is removed by drilling a portion of the bond shelf.

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21-34. (Cancelled)

35. (Previously Presented) The method as recited in claim 15, wherein  
the forming of the conductive strip further includes

forming a portion of the conductive strip around onto the top surface of the bond  
shelf to couple to the bond pad on the top surface of the bond shelf.

36. (Previously Presented) The method as recited in claim 35, wherein

the portion of the conductive strip around on the top surface of the bond shelf to  
further anchor the conductive strip to the housing.

37. (Previously Presented) The method as recited in claim 15, wherein  
the forming of the conductive strip further includes

forming a portion of the conductive strip around onto the top surface of the bond  
shelf to form another bond pad on the top surface of the bond shelf.

38. (Previously Presented) The method as recited in claim 37, wherein

the portion of the conductive strip around on the top surface of the bond shelf to  
further anchor the conductive strip to the housing.

39. (Cancelled).

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40. (Previously Presented) A method of for assembling an electronic package, comprising:
- forming a housing which has a bond pad located on a top surface of a bond shelf, the bond shelf having an inside surface along an edge of the bond shelf;
- plating a conductive material along the inside surface of the bond shelf; and
- removing a portion of the conductive material along the inside surface of the bond shelf to form a pair of separate conductive strips along the inside surface of the bond shelf, the portion of the conductive material is removed by drilling into the edge of the bond shelf including the conductive material and the inside surface.
41. (Cancelled)
42. (Previously Presented) The method of claim 40, wherein,
- the plating of the conductive material onto the inside surface of the bond shelf includes
- masking surfaces of the housing that are not to be plated and
- leaving surfaces of the housing unmasked that are to be plated, including the inside surface of the bond shelf that is to be plated.
43. (Previously Presented) The method of claim 42, wherein
- the plating of the conductive material further includes
- plating copper onto the unmasked surfaces of the housing, and
- plating gold onto the copper.

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44. (Previously Presented) The method of claim 43, wherein  
the portion of the conductive material is removed by  
drilling into the edge of the bond shelf including the conductive material and the  
inside surface.
45. (Previously Presented) The method of claim 40, wherein  
the plating of the conductive material further includes  
plating a portion of the conductive material from the inside surface around onto  
the top surface of the bond shelf to couple to the bond pad on the top surface of the bond  
shelf.
46. (Previously Presented) The method of claim 45, wherein  
the portion of the conductive material plated around onto the inside surface of the  
bond shelf to further anchor the conductive material to the housing.
47. (Previously Presented) The method of claim 40, wherein  
the plating of the conductive material further includes  
plating a portion of the conductive material from the inside surface around onto  
the top surface of the bond shelf to form another bond pad on the top surface of the bond  
shelf.
48. (Previously Presented) The method of claim 47, wherein

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the portion of the conductive material plated around onto the top surface of the bond shelf to further anchor the conductive material to the housing.

49. (Previously Presented) The method of claim 40, further comprising:  
mounting an integrated circuit to the housing and connecting the integrated circuit to the bond pad.

50. (Cancelled).

51. (Previously Presented) The method as recited in claim 52, wherein  
the conductive strip is formed by plating a conductive material onto the rectangular cavity wall of the bond shelf.

52. (Previously Presented) A method for assembling an electronic package, comprising:  
forming a housing which has a plurality of bond pads located on a top surface of a bond shelf, the bond shelf forming a rectangular cavity wall along an inner side of the bond shelf;  
forming a conductive strip lengthwise along the rectangular cavity wall of the bond shelf;  
and

removing portions of the conductive strip along the rectangular cavity wall of the bond shelf to form a plurality of separate conductive strips along the rectangular cavity wall of the bond shelf, portions of the conductive strip are removed by drilling a portion of the rectangular cavity wall of the bond shelf including the conductive strip.

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53. (Previously Presented) The method as recited in claim 52, further comprising:  
mounting an integrated circuit to the housing and connecting the integrated circuit to at least one of the plurality of bond pads.

54. (Cancelled)

55. (Previously Presented) The method as recited in claim 52, wherein  
the conductive strip is formed along the rectangular cavity wall of the bond shelf by  
masking surfaces of the bond shelf except for portions of the bond shelf to be  
plated, the rectangular cavity wall of the bond shelf being unmasked, and  
plating a conductive material onto the rectangular cavity wall of the bond shelf.